

Title (en)
DEVICE AND METHOD FOR TREATING WAFERS

Title (de)
VORRICHTUNG UND VERFAHREN ZUR BEARBEITUNG VON WAFERN

Title (fr)
DISPOSITIF ET PROCÉDÉ DE TRAITEMENT DE PLAQUETTES

Publication
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Application
EP 20703704 A 20200130

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Abstract (en)
[origin: WO2020157229A1] The present invention relates to a device and method for treating wafers. According to the invention, the wafers are transported in vertical alignment through the process solution used for treating the wafers, as a result of which it is possible to increase the throughput, simplify the after-treatment of the exhaust air, and reduce the consumption of components in the process solution. The invention can be used, inter alia, in the production of solar cells, or of printed circuit boards, for example printed circuit boards for the electrical industry.

IPC 8 full level
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